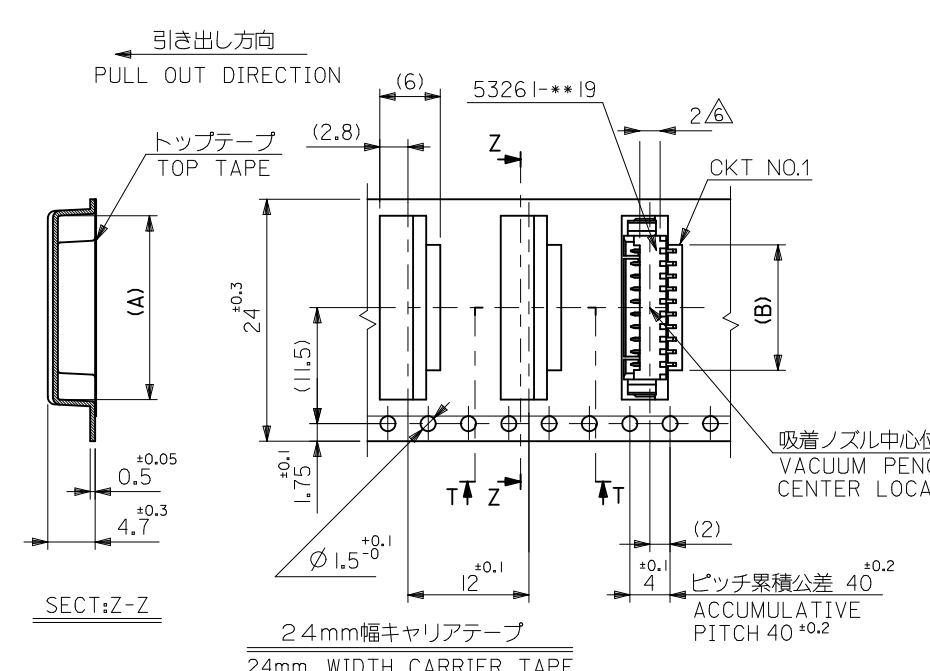
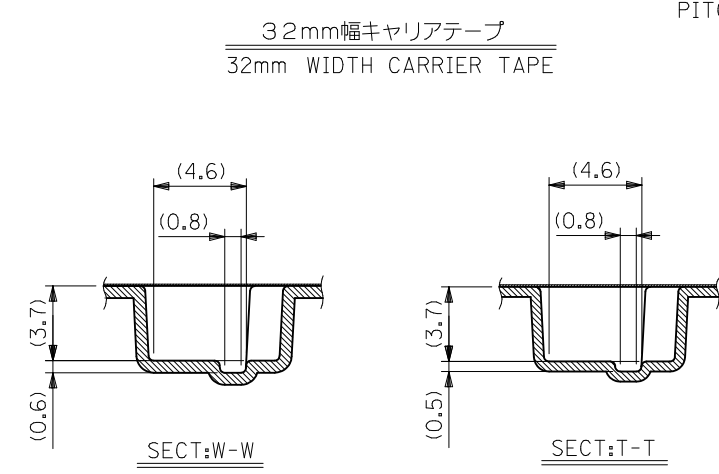
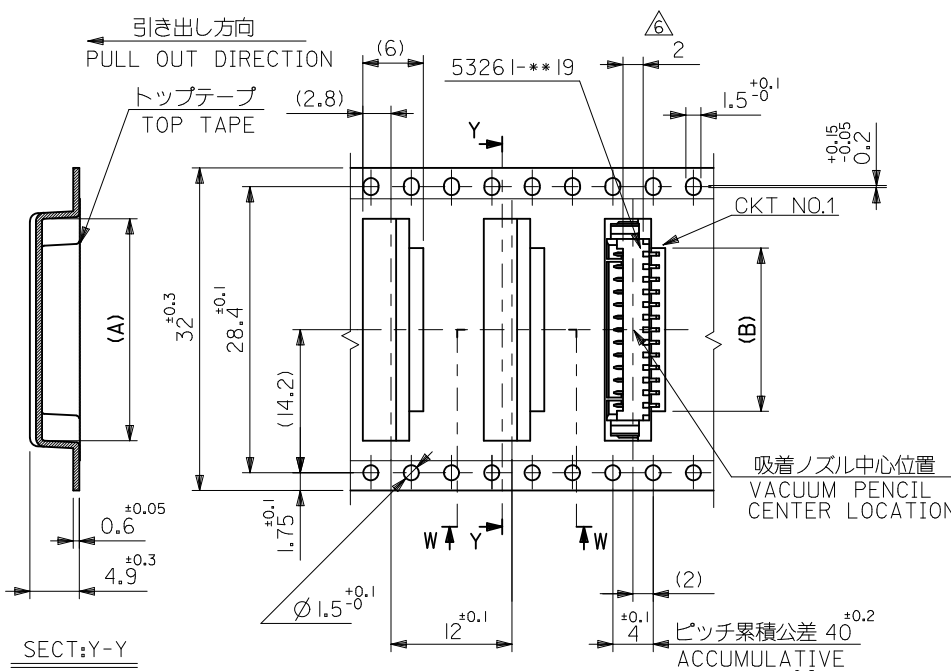


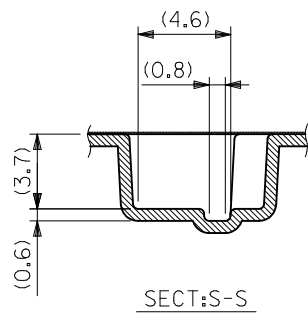
53261-****	WAFER ASSY	MODEL NO./MATERIAL NO.
50079-****	TERMINAL	
51021-****	HOUSING	

RELEASED EC NO: J2006-2426 DRWN:YAOYAGI 2006/02/02 CHKD:YMAEDA 2006/02/03 APPR:NUKITA 2006/02/07 REV 0	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± ---	DRAWN BY Y.AOYAGI	DATE 2006/01/30	TITLE 1.25 W-TO-B CONN. 51021,53261 MATING CROSS SECTION				
		10 OVER 30 UNDER	± ---	CHECKED BY Y.MAEDA	DATE 2006/01/30					
		30 OVER	± ---	APPROVED BY N.UKITA	DATE 2006/01/30	MOLEX INCORPORATED				
		ANGULAR ±--- °		MATERIAL NO.			DOCUMENT NO.			SHEET NO.
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART			SD-51021-002			1 OF 1
	REV	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								

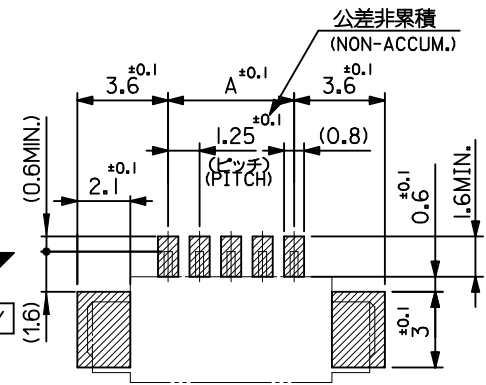
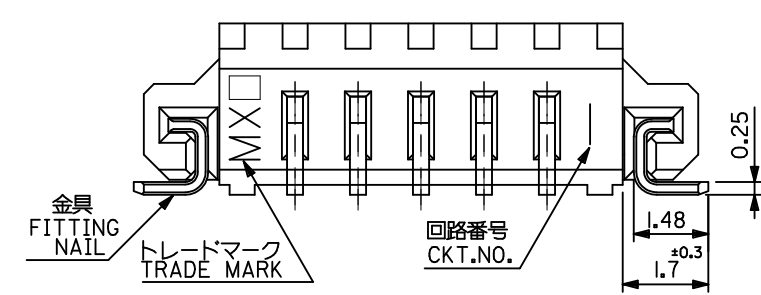
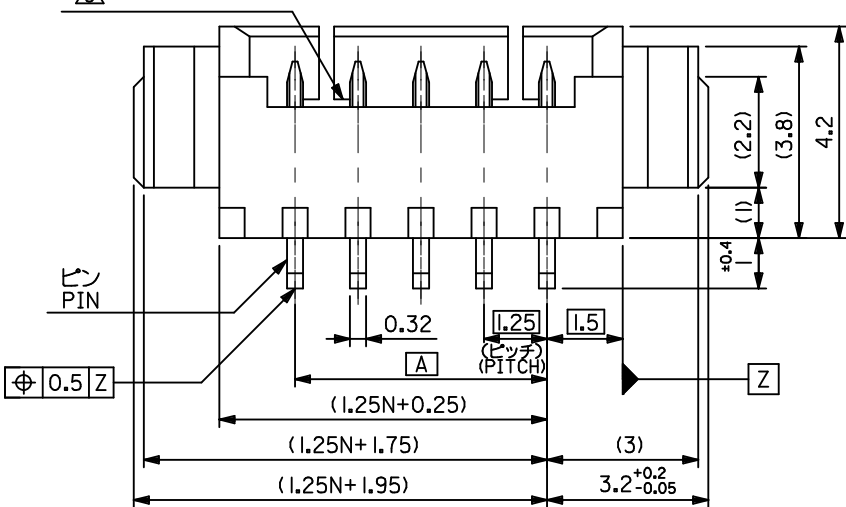
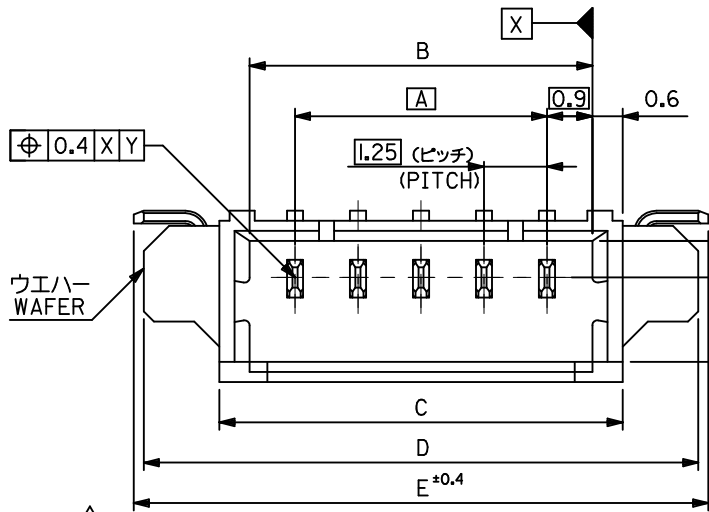


32	37.4	33.4	16.2	22	53261-1371	13
			14.95	20.75	-1271	12
			13.7	19.5	-1171	11
24	29.4	25.4	12.45	18.25	-1071	10
			11.2	17	-0971	9
			9.95	15.75	-0871	8
			8.7	14.5	-0771	7
			7.45	13.25	-0671	6
			6.2	12	-0571	5
			4.95	10.75	53261-0471	4
			53261-0471			
キャリアテープ幅 CARRIER TAPE WIDTH	D	C	B	A	EMBOSSD TAPE PACKAGE オーダー番号 ORDER NO	種数 CKT

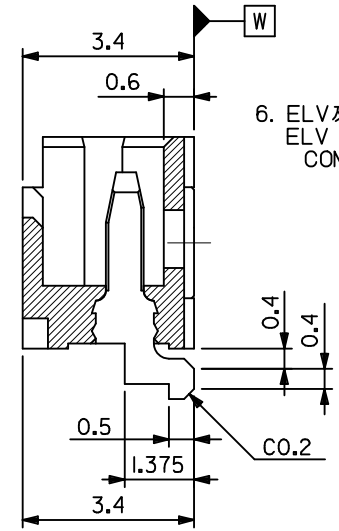
REVISED	EC NO:	DRWN: YGOTO	CHKD: KASAKAWA	APPR:	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE	
								MM ONLY		---	METRIC	PROJECTION	
						10 UNDER	± 0.2	DRAWN BY	DATE	TITLE			
						10 OVER 30 UNDER	± 0.25	H. SHIMABUKUR	'04/02/06				
						30 OVER	± 0.3	CHECKED BY	DATE	1.25 W/B CONN WAFER ASSY FOR SMT EMBSTP PKG			
						ANGULAR ±3 °	NUKITA	'04/02/06	2010/02/18				
						DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO.		MOLEX INCORPORATED			
		SEE TABLE & SHEET 1.3		DOCUMENT NO.									
D	REV	2010/02/17	2010/02/17	2010/02/17	2010/02/17			SD-53261-023		SHEET NO.			
										2 OF 3			
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION													



MODEL NO.			53261-**-71			44		49.4	45.4	18.7 17.45	24.5 23.25	53261-I-1571 53261-I-1471		I5 I4
						キャリアテープ幅 CARRIER TAPE WIDTH		D	C	B	A	EMBOSSD TAPE PACKAGE オーダー番号 ORDER NO.		極数 CKT.
REVISED EC NO. DRWN:Y.GOTO CHKD:K.SAKAWA APPR:	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)				DIMENSION STYLE MM ONLY				SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER ±0.2		DRAWN BY DATE H. SHIMABUKUR '04/02/06		TITLE 1.25 W/B CONN WAFER ASSY FOR SMT EMBSTP PKG								
		10 OVER 30 UNDER ±0.25		CHECKED BY DATE K. TOJO '04/02/06										
		30 OVER ±0.3		APPROVED BY DATE NUKITA 2010/02/18										
		ANGULAR ±3 °		MATERIAL NO.				DOCUMENT NO.				SHEET NO.		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE & SHEET 1.2				SD-53261-023				3 OF 3		
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION														



参考基板レイアウト
RECOMMENDED P.C.BOARD PATTERN DIM.(REF.)
(SCALE 5:1)



【断面図】
[CROSS SECTION]

注記 NOTES

1. 嵌合相手: 51021 シリズ
MATES WITH: 51021 SERIES
2. 材質 MATERIAL
ウエハー: NYLON46, UL94V-0
ピン: リン青銅
PIN: PHOS-BRO
: 銅メッキ 1.0マイクロメートル以上
: TIN 1.0 MICROMETER MINIMUM
: ニッケル下地 1.0マイクロメートル以上
: NICKEL(UNDER PLATING) 1.0 MICROMETER MINIMUM
金具: リン青銅
FITTING NAIL: PHOS-BRO
: 銅メッキ 1.0マイクロメートル以上
: TIN 1.0 MICROMETER MINIMUM
: ニッケル下地 1.0マイクロメートル以上
: NICKEL(UNDER PLATING) 1.0 MICROMETER MINIMUM
- △ ロック窓は2, 3極は1箇所, 4極以上は2箇所とする。
LOCKING WINDOW:
ONE PLACE FOR 2 AND 3 CKT. AND
TWO PLACES FOR MORE THAN 3 CKT.
4. ソルダテール部のスレ量及び金具(補強板)のスレ量は基準面 [W] に対し、上方向 0.05 MAX.、下方向に 0.1 MAX. とする。 [W]
OFFSET BETWEEN BASIS PLANE
TO SOLDER TAIL BOTTOM AND
FITTING NAIL BOTTOM:
UPPER SIDE: 0.05MAX.
LOWER SIDE: 0.1MAX.
5. 本製品は 53261-***10 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53261-***10

26.4	26	23	21.8	20	53261-1719	17	
23.9	23.5	20.5	19.3	17.5	-1519	15	
22.65	22.25	19.25	18.05	16.25	-1419	14	
21.4	21	18	16.8	15	-1319	13	
20.15	19.75	16.75	15.55	13.75	-1219	12	
18.9	18.5	15.5	14.3	12.5	-1119	11	
17.65	17.25	14.25	13.05	11.25	-1019	10	
16.4	16	13	11.8	10	-0919	9	
15.15	14.75	11.75	10.55	8.75	-0819	8	
13.9	13.5	10.5	9.3	7.5	-0719	7	
12.65	12.25	9.25	8.05	6.25	-0619	6	
11.4	11	8	6.8	5	-0519	5	
10.15	9.75	6.75	5.55	3.75	-0419	4	
8.9	8.5	5.5	4.3	2.5	-0319	3	
9	7.65	7.25	4.25	3.05	1.25	53261-0219	2
1.	E	D	C	B	A	MATERIAL. NO.	極數 CKT.

REVISED EC NO: J2012-1315 2012/04/16 DRWN: NITO CHKD: KASAKAWA 2012/04/16 APPR: Y010 2012/04/16	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	±0.2	DRAWN BY HSHIMABU	DATE 04/02/06	1.25 WIRE TO BOARD WAFER ASS FOR SMT molex SD-53261-024 SHEET NO. 1 OF 1			
		10 OVER 30 UNDER	±0.25	CHECKED BY KTOJO	DATE 04/02/06				
		30 OVER	±0.3	APPROVED BY MSASAO	DATE 04/02/06				
G	REV	ANGULAR ±3 °		MATERIAL NO. SEE DRAWING		DOCUMENT NO. SD-53261-024			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			